

IN THE CLAIMS:

Claims 1-3 have been amended herein. All of the pending claims 1 through 3 are presented, pursuant to 37 C.F.R. §§ 1.121(c)(1)(i) and 1.121(c)(3), in clean form below. Please enter these claims as amended. Attached is a marked-up version of the claims amended herein pursuant to 37 C.F.R. § 1.121(c)(1)(ii).

As 1. (Amended) An assembly method for a semiconductor device assembly using a wire bonding device having an upper clamp member and a lower clamp member, said method comprising:
forming a strip of lead frames, said strip having opposed rails, having dam bars between said opposed rails, having at least two inner leads, having at least two outer leads, having a die, mount paddle and having at least one integral clamping tab, said at least one integral clamping tab extending outwardly for contact by said upper clamp member;
attaching a semiconductor device to said die mount paddle, said semiconductor device having a plurality of bond pads;
aligning said strip of lead frames on said lower clamp member of said wire bonding device having said upper clamp member overlying portions of said at least two inner leads and portions of said at least two outer leads of said at least one integral clamping tab; and
attaching at least two bond wires to said plurality of bond pads of said semiconductor device and said portions of said at least two inner leads.

2. (Amended) The method of claim 1, further comprising:
forming said die mount paddle having an upper surface thereof at a level below an upper level of said at least two inner leads; and
deforming said at least one integral clamping tab to clamp portions thereof.

As
Cont

3. (Amended) The method of claim 1, further comprising:
removing said strip of lead frames and said semiconductor device from said lower clamp member;
and
encapsulating a portion of said strip of lead frames, said semiconductor device, and said at least
two bond wires extending between said strip of lead frames and said semiconductor device
in a material.
